



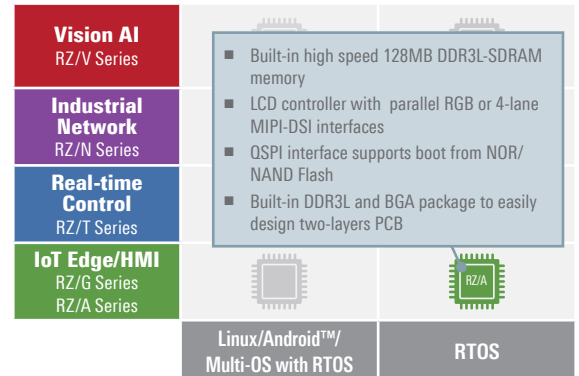
Optimize Speed and Graphics Performance for High-Definition HMI

RENESAS RZ/A3M GROUP

64bit Arm® Cortex®-A55 MPU (1GHz) with built-in DDR3L SDRAM

The RZ/A3M MPUs based on the Arm® Cortex®-A55 (CA55) core with NEON™ extension and built-in large capacity 128MB DDR3L memory are equipped with a feature set optimized to address diverse human-machine interface (HMI) for consumer, smart home and building automation, healthcare, industrial applications, and office automation market segments.

The RZ/A3M MPUs also integrate features such as high-resolution Graphics LCD controller with parallel RGB and 4-lane MIPI-DSI interfaces to display panels, 2D graphics drawing engine, support QSPI NOR/NAND Flash for large-size programs, and 244 pin LFBGA package which is ideal for 2-layers board design.



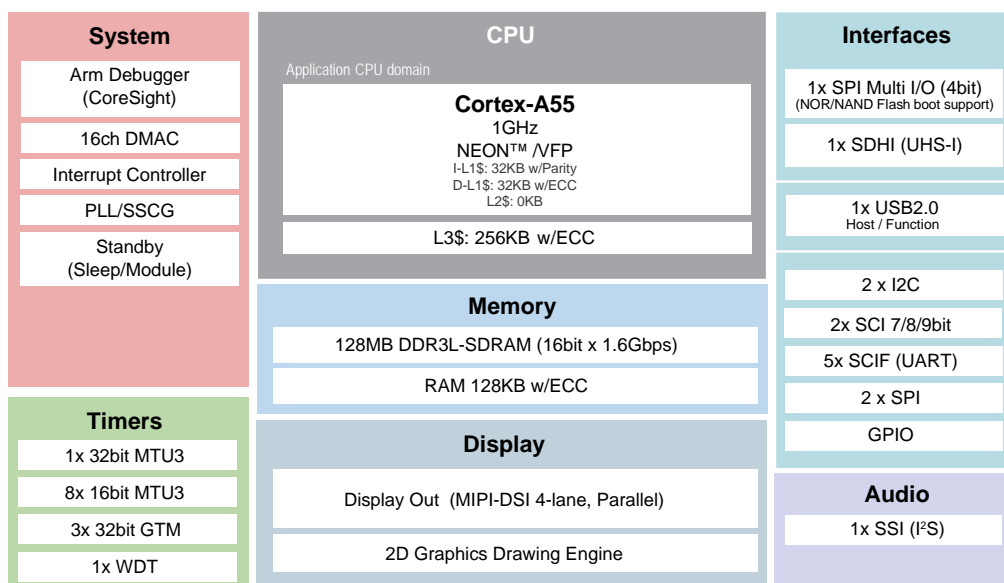
Features

- 64bit 1GHz Arm Cortex-A55 with NEON
- Built-in 128MB DDR3L SDRAM
- LCD controller up to WXGA (1280x800) with parallel RGB and MIPI-DSI (4lane) interface
- 2D Drawing engine
- QSPI NOR/NAND Flash boot
- Enable 2-layer PCB design
- SDHI for high-speed Wi-Fi® module
- I²S for audio interface
- USB 2.0 Interface for USB camera
- UART/SPI/I²C for sensors

Applications

- Consumer products
- Smart home and building automation
- Healthcare
- Industrial applications
- Office automation

Block Diagram



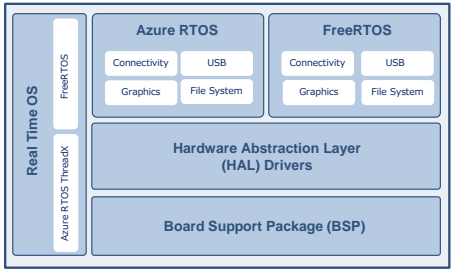
* Due to pin multi-functionality, not all functions can be simultaneously used.

RENESAS RZ/A3M GROUP

Software Package

The Renesas RZ/A Flexible Software Package (FSP) is designed to provide easy-to-use, scalable, high-quality software for embedded system designs using RZ MPUs.

The FSP is based on an open software ecosystem of production-ready drivers, supporting FreeRTOS, Azure RTOS or bare-metal programming. It also includes a selection of other middleware stacks, providing great flexibility for migrating code from older systems or developing new applications from scratch.



Flexible Software Package (FSP)

Tools and Support

The e² studio IDE provides support with intuitive configurators and intelligent code generation to make programming and debugging easier and faster.

	Renesas
Development Environments	e ² studio
Compilers	GNU Arm Embedded Toolchain
ICEs	J-Link series from Segger
Supported RTOS	FreeRTOS, Azure RTOS

Evaluation Kits

- Evaluate key features of RZ/A3M MPU and develop high-resolution HMI and other embedded systems applications
- Includes MIPI graphics expansion board (5inch TFT display, 720*1280 pixel)
- Features on-board debugging using SEGGER-J-Link
- Order the kit and download documentation, design package, development tools, and software at www.renesas.com/ek-rza3m
- Orderable part number: **RTK9EKZA3MS10001BE**



Ordering Information

	R9A07G066M04GBG
CPU/Frequency	Cortex-A55/1.0GHz
RAM	128MB DDR3L 128KB SRAM
Supported Flash	Quad SPI NOR/NAND Flash
LCD interface	Parallel/ MIPI 4-lane
Connectivity	1xUSB2.0(Host/Device) 1xSDHI
Tj	-40 to 110°C
Package	BGA 244pin 17mm x 17mm 0.8mm pitch

For more information, visit
www.renesas.com/RZA3M



renesas.com

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan
www.renesas.com

Document No. R01PM0105EU0100

Trademarks

Arm® and Cortex® are registered trademarks of Arm Limited. Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.

Contact information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit:
www.renesas.com/contact/